

Welcome to MRSI Solutions Newsletter. This periodic newsletter provides information on our latest happenings and product updates.

Many thanks to our loyal customers for their continued interest in our products.

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## MRSI Solutions

### For Dispense and Assembly

#### Dispensing Solutions Update

Newport has been busy adding new dispense features to the MRSI-175Ag Precision Dispense System and the dispensing options on our family of die bonders. This further enhances the capability of our systems for precision dispensing for advanced packaging solutions. These new features include the following:

- **New Dispense Pump Technologies**

In addition to rotary style positive displacement pumps, the user can now select jetting, stamping and time/pressure pumps including fully digital enhanced time/pressure with an integrated Mushashi Engineering controller.

- **Confocal Height Sensor**

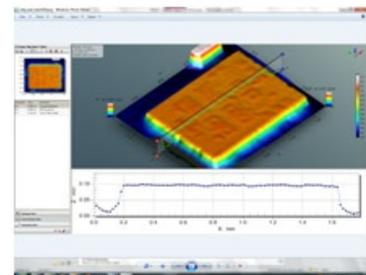
A confocal height sensor is used to precisely determine dispense heights. The advantage of the confocal sensor is that it allows vertical measurements in deep cavities and in close proximity to walls and other obstructions.

- **Real Time Video**

Real time video is available for dispense and pick and place for process monitoring of dispense and assembly.

- **Volume Scanning and Display Software**

The system scans an area with the confocal height sensor. The 3D data is then processed to get a volume measurement. The system reports if the result is outside the control limits. An image of the surface topography based on the scanned data is displayed during production.



- **Image Storage for Verification and Traceability**

This option allows user to select and store images for each dispense and placement in a program.

The next several issues will provide more detailed descriptions of these exciting new features and benefits.

## Assembly Solutions Update

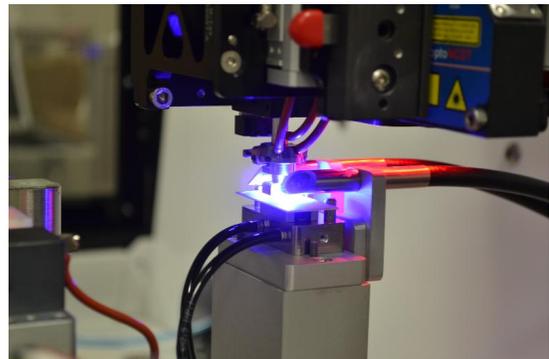
Our industry-standard family of high-precision die bonders continues to improve and expand and now includes the following:

- MRSI-M3 Ultra High Precision Die Bonder with 3 Micron Placement Accuracy
- MRSI-M5 Ultra High Precision Die Bonder with 5 Micron Placement Accuracy
- MRSI-705 High Precision Die Bonder with 8 Micron Placement Accuracy
- MRSI-605 High Precision Die Bonder with 10 Micron Placement Accuracy



As the needs for greater accuracy increase the demand for in-situ UV curing also increases. UV curing during assembly provides the advantage of eliminating post bond cure movement. Our die bonders are available with a wide range of UV dispensing and curing options including integrated automatic material handling.

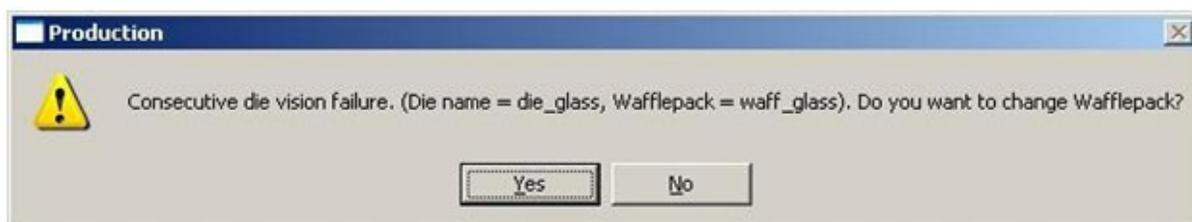
These and other new available features and options will be explained in more detail in subsequent newsletters.



## Applications Corner

Newport's Workcell software is always being enhanced with new software features. One recent addition is the ability for Operators to quickly change the waffle pack setting during production. The reality of day to day production is that die often come from the stockroom in a different waffle pack than the one they were taught. Now the Operator can make a fast change and continue production. This is a special provision for Operator level privileges, so there is no risk that any of the other parameters in the die database will be affected. There is no reason to call an engineer to re-teach and the system is back in operation in seconds.

Contact Newport for more details.



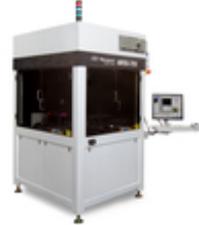
**MRSI - M3**  
**Assembly Work Cell**



**MRSI - M5**  
**Assembly Work Cell**



**MRSI-705**  
**Assembly Work Cell**



**MRSI-175Ag**  
**Epoxy Dispenser**



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